

●不可使用電子計算機

熱力學

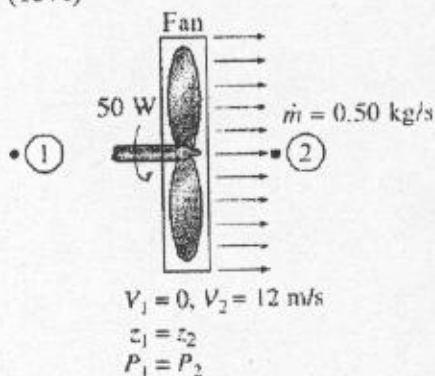
1. Prove 1st TdS eqn.  $TdS = dU + PdV$  and 2<sup>nd</sup> TdS eqn.  $TdS = dH + VdP$  (10%)

2. For a closed system, prove its exergy (X) equals to  
 $X = W_c = (U - U_0) + p_0(V - V_0) - T_0(S - S_0) + KE + PE$  (10%)

Where U, V, S KE and PE denote internal energy, volume, entropy, kinetic energy, and potential energy of the system at a specified state.  $U_0, V_0$  and  $S_0$  denote internal energy, volume, and entropy of the system at the dead state.

3. During the isothermal heat rejection process of a Carnot cycle, the working fluid experiences an entropy change ( $\Delta S$ ) of  $-0.8 \text{ kJ/K}$ . If the heat sink is  $95^\circ\text{C}$ , determine (a) the amount of heat transfer, (b) entropy change of the sink, (c) the total entropy change for this process. (15%, @ 5%)

4. Determine the mechanical efficiency of a fan ( $\eta_{\text{mech, fan}}$ ) shown below. (15%)

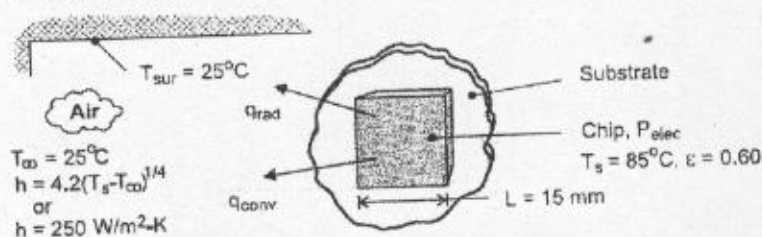


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5. (15%) (a). Please describe the physical mechanisms of conduction, convection and radiation, and write their rate equations. (10%)  
 (b). What is the difference between natural convection and force convection? (5%)

6. (20%) Chips of which  $L=15\text{mm}$  on a side are mounted to a substrate that is installed in an enclosure whose walls and air are maintained at a temperature of  $T_{\text{sur}}=T_{\infty}=25\text{C}$ . The chip have an emissivity of  $\epsilon=0.60$  and a maximum allowable temperature of  $T_s=85\text{C}$ .  
 (a). If heat is rejected from the chips by radiation and natural convection, what is the maximum operating power of each chip? The convection coefficient depends on the chip-to-air temperature difference and may be approximated as  $h=C(T_s-T_{\infty})$  where  $C=4.2\text{ W/m}^2\text{K}^{5/4}$ . (10%)  
 (b) If a fan is used to maintain air flow through the enclosure and heat transfer is by forced convection, with  $h=250\text{W/m}^2\text{K}$ , what is the maximum operating power? (10%)



7. (15%) A thin walled copper tubes of radius  $r_1$  is used to transport a low temperature refrigerant and is at a temperature  $T_1$  that is less than that of the ambient air at  $T_{\infty}$  around the tube. Is there an optimum thickness associated with application of insulation to the tube. Please construct the thermal circuit of heat flow resistance. And prove the optimal insulation radius is  $r_{\text{cr}} = k/h$ .